

Surface Mount Schottky Barrier Rectifier

FEATURES

- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Meets environmental standard MIL-S-19500D
- Moisture sensitivity:level 1, per J-STD-020
- Solder dip 275 °C, 10 s
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



DO-214AC (SMA)

TYPICAL APPLICATIONS

For use in general purpose rectification of lighting, power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication.

PRIMARY CHARACTERISTICS	
I _{F(AV)}	1 A
V _{RRM}	20 V to 100 V
I _{FSM}	30A
V _F	0.42V,0.5V,0.68V
T _J max.	125 °C ,150°C

MECHANICAL DATA

Case: DO-214AC, molded epoxy body, Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22B-106

Polarity: Laser Band Denotes Cathode Band

MAXIMUM RATINGS (TA = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	SL12A	SL13A	SL14A	SL15A	SL16A	SL17A	SL18A	SL19A	SL110A	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	70	80	90	100	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	49	56	63	70	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	70	80	90	100	V
Maximum average forward rectified current at TL (See Fig.1)	I _{F(AV)}	1								A	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30								A	
Operating junction temperature range	T _J	- 55 to + 125			- 55 to + 150			°C			
Storage temperature range	T _{stg}	- 55 to + 150								°C	

ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	SL12A	SL13A	SL14A	SL15A	SL16A	SL17A	SL18A	SL19A	SL110 A	UNIT
Maximum instantaneous forward voltage	IF=1 A	VF		0.42		0.5		0.68				V
Maximum DC reverse current at rated DC blocking voltage	TA=25°C TA=100°C	IR				0.2						mA
Typical junction capacitance	4.0 V, 1 MHz	CJ				85						pF

THERMAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	SL12A	SL13A	SL14A	SL15A	SL16A	SL17A	SL18A	SL19A	SL110A	UNIT
Maximum thermal resistance	R _{θJA} (1)					0.197					°C/W
	R _{θJT} (2)						0.197				

Notes: (1) Thermal resistance from junction to ambient, 0.197 × 0.197" (5.0 × 5.0mm) copper pads to each terminal
(2) Thermal resistance from junction to terminal, 0.197 × 0.197" (5.0 × 5.0mm) copper pads to each terminal

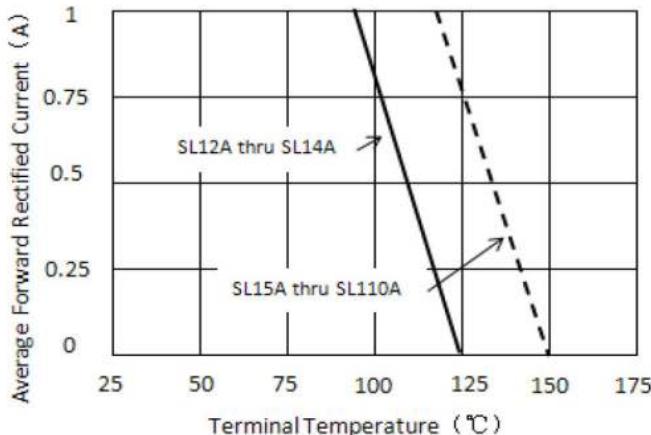
RATINGS AND CHARACTERISTICS CURVES
(T_A = 25 °C unless otherwise noted)

Figure 1. Forward Current Derating Curve

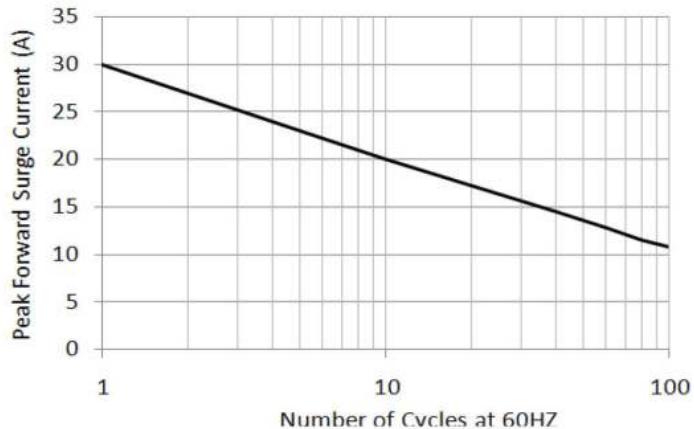


Figure 2. Maximum Non-repetitive Peak Forward Surge Current

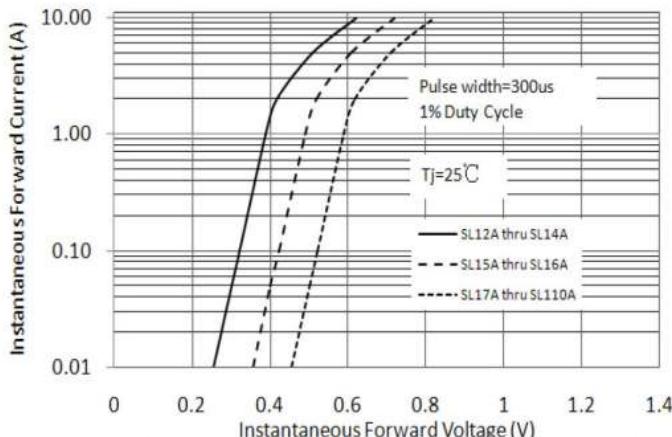


Figure 3. Typical Instantaneous Forward Characteristics

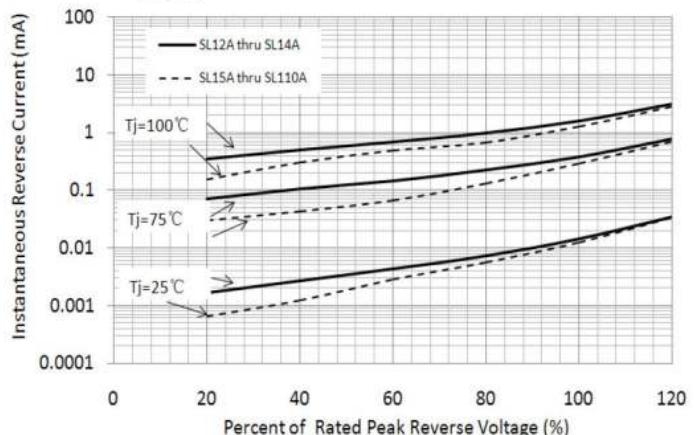


Figure 4. Typical Reverse Characteristics

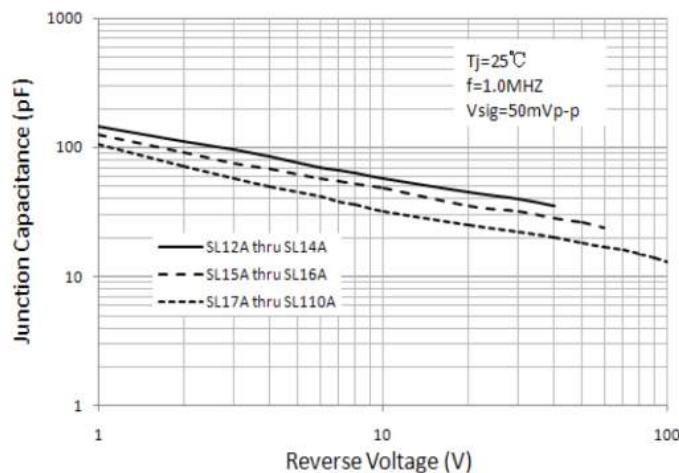


Figure 5. Typical Junction Capacitance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)